

RS-232 TRANSCEIVER WITH SPLIT SUPPLY PIN FOR LOGIC SIDE

Check for Samples: [MAX3386E](#)

FEATURES

- V_L Pin for Compatibility With Mixed-Voltage Systems Down to 2.5 V on Logic Side
- Enhanced ESD Protection on RIN Inputs and DOUT Outputs
 - ± 15 -kV Human-Body Model
 - ± 15 -kV IEC 61000-4-2, Air-Gap Discharge
 - ± 8 -kV IEC 61000-4-2, Contact Discharge
- Low 300- μ A Supply Current
- Specified 250-kbps Data Rate
- 1- μ A Low-Power Shutdown
- Meets EIA/TIA-232 Specifications Down to 3 V

APPLICATIONS

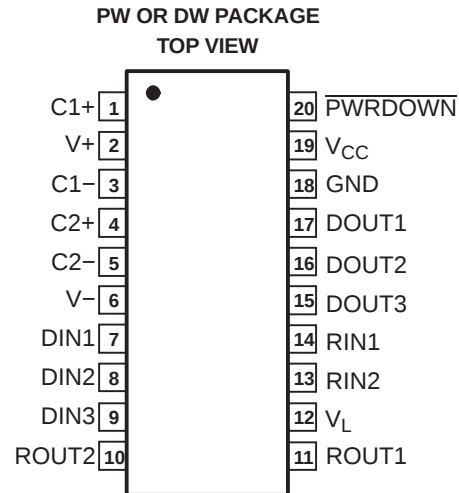
- Hand-Held Equipment
- PDAs
- Cell Phones
- Battery-Powered Equipment
- Data Cables

DESCRIPTION/ORDERING INFORMATION

The MAX3386E is a three-driver and two-receiver RS-232 interface device, with split supply pins for mixed-signal operations. All RS-232 inputs and outputs are protected to ± 15 kV using the IEC 61000-4-2 Air-Gap Discharge method, ± 8 kV using the IEC 61000-4-2 Contact Discharge method, and ± 15 kV using the Human-Body Model.

The charge pump requires only four small 0.1- μ F capacitors for operation from a 3.3-V supply. The MAX3386E is capable of running at data rates up to 250 kbps, while maintaining RS-232-compliant output levels.

The MAX3386E has a unique V_L pin that allows operation in mixed-logic voltage systems. Both driver in (DIN) and receiver out (ROUT) logic levels are pin programmable through the V_L pin. The MAX3386E is available in a space-saving thin shrink small-outline package (TSSOP).



ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾ (2)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	TSSOP – PW	MAX3386ECPWR	MP386EC
	SOIC – DW	MAX3386ECDW	MAX3386EC
–40°C to 85°C	TSSOP – PW	MAX3386EIPWR	MP386EI
	SOIC – DW	MAX3386EIDW	MAX3386EI

- (1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.
- (2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

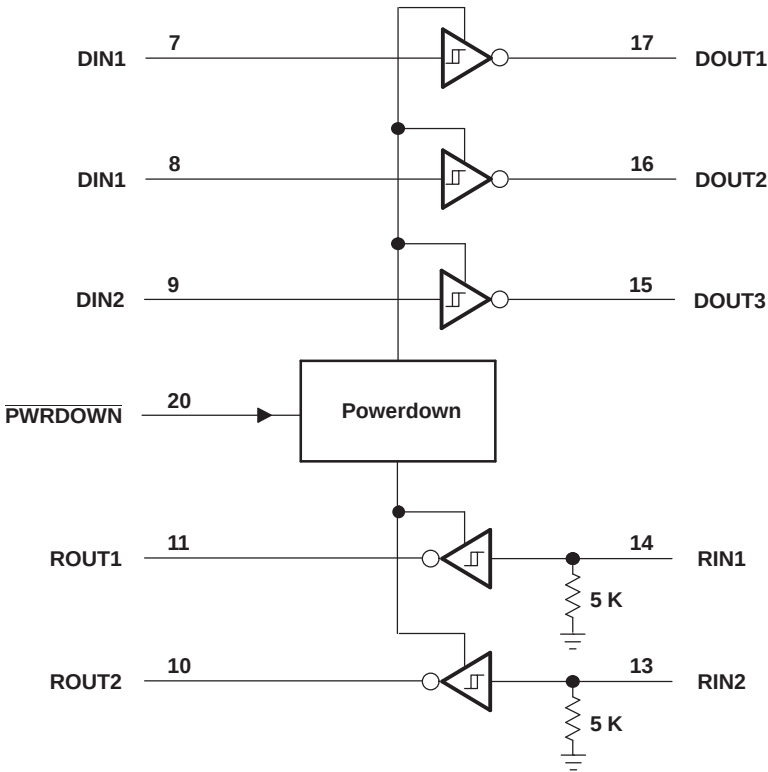


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Table 1. TRUTH TABLE (SHUTDOWN FUNCTION)

$\overline{\text{PWRDWN}}$	DRIVER OUTPUTS	RECEIVER OUTPUTS	CHARGE PUMP
L	High-Z	High-Z	Inactive
H	Active	Active	Active

FUNCTIONAL BLOCK DIAGRAM



TERMINAL FUNCTIONS

TERMINAL		DESCRIPTION
NAME	NO.	
C1+	1	Positive terminal of the voltage-doubler charge-pump capacitor
V+	2	5.5-V supply generated by the charge pump
C1-	3	Negative terminal of the voltage-doubler charge-pump capacitor
C2+	4	Positive terminal of the inverting charge-pump capacitor
C2-	5	Negative terminal of the inverting charge-pump capacitor
V-	6	-5.5-V supply generated by the charge pump
DIN1 DIN2 DIN3	7 8 9	Driver inputs
ROUT2 ROUT1	10 11	Receiver outputs. Swing between 0 and V _L .
V _L	12	Logic-level supply. All CMOS inputs and outputs are referenced to this supply.
RIN2 RIN1	13 14	RS-232 receiver inputs
DOUT3 DOUT2 DOUT1	15 16 17	RS-232 driver outputs
GND	18	Ground

TERMINAL FUNCTIONS (continued)

TERMINAL		DESCRIPTION
NAME	NO.	
V _{CC}	19	3-V to 5.5-V supply voltage
$\overline{\text{PWRDWN}}$	20	Powerdown input L = Powerdown H = Normal operation

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC} to GND			−0.3	6	V
V _L to GND			−0.3	V _{CC} + 0.3	V
V+ to GND			−0.3	7	V
V− to GND			0.3	−7	V
V+ + V− ⁽²⁾				13	V
V _I	Input voltage	DIN, $\overline{\text{PWRDWN}}$ to GND	−0.3	6	V
		RIN to GND		±25	
V _O	Output voltage	DOUT to GND		±13.2	V
		ROUT	−0.3	V _L + 0.3	
Short-circuit duration DOUT to GND				Continuous	
Continuous power dissipation		T _A = 70°C, 20-pin TSSOP (derate 7 mW/°C above 70°C)		559	mW
T _J	Junction temperature			150	°C
T _{stg}	Storage temperature range		−65	150	°C
Lead temperature (soldering, 10 s)				300	°C

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.
- (2) V+ and V– can have maximum magnitudes of 7 V, but their absolute difference cannot exceed 13 V.

Recommended Operating Conditions

				MIN	MAX	UNIT
V _{CC}	Supply voltage			3	5.5	V
V _L	Supply voltage			2.25	V _{CC}	V
Input logic threshold low	DIN, $\overline{\text{PWRDWN}}$	V _L = 3 V or 5.5 V		0.8		V
		V _L = 2.3 V		0.6		
Input logic threshold high	DIN, $\overline{\text{PWRDWN}}$	V _L = 5.5 V		2.4		V
		V _L = 3 V		2.0		
		V _L = 2.7 V		1.4		
Operating temperature			MAX3386ECPWR	0	70	°C
			MAX3386EIPWR	−40	85	
Receiver input voltage				−25	25	V

Electrical Characteristics

over operating free-air temperature range, V_{CC} = V_L = 3 V to 5.5 V, C1–C4 = 0.1 μF (tested at 3.3 V ± 10%), C1 = 0.047 μF, C2–C4 = 0.33 μF (tested at 5 V ± 10%) (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
DC Characteristics (V_{CC} = 3.3 V or 5 V, T_A = 25°C)					
Powerdown supply current	$\overline{\text{PWRDWN}}$ = GND, All inputs at V _{CC} or GND		1	10	μA

- (1) Typical values are at V_{CC} = V_L = 3.3 V, T_A = 25°C.

Electrical Characteristics (continued)

over operating free-air temperature range, $V_{CC} = V_L = 3\text{ V}$ to 5.5 V , $C1\text{--}C4 = 0.1\text{ }\mu\text{F}$ (tested at $3.3\text{ V} \pm 10\%$), $C1 = 0.047\text{ }\mu\text{F}$, $C2\text{--}C4 = 0.33\text{ }\mu\text{F}$ (tested at $5\text{ V} \pm 10\%$) (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
Supply current	$\overline{\text{PWRDWN}} = V_{CC}$, No load		0.3	1	mA

ESD Protection

PARAMETER	TEST CONDITIONS	TYP	UNIT
RIN, DOUT	Human-Body Model	± 15	kV
	IEC 61000-4-2 Air-Gap Discharge	± 15	
	IEC 61000-4-2 Contact Discharge	± 8	

RECEIVER SECTION

Electrical Characteristics

over operating free-air temperature range, $V_{CC} = V_L = 3\text{ V}$ to 5.5 V , $C1\text{--}C4 = 0.1\text{ }\mu\text{F}$ (tested at $3.3\text{ V} \pm 10\%$), $C1 = 0.047\text{ }\mu\text{F}$, $C2\text{--}C4 = 0.33\text{ }\mu\text{F}$ (tested at $5\text{ V} \pm 10\%$), $T_A = T_{MIN}$ to T_{MAX} (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP ⁽¹⁾	MAX	UNIT
I_{off}	Output leakage current	ROUT, receivers disabled			± 0.05	± 10	μA
V_{OL}	Output voltage low	$I_{OUT} = 1.6\text{ mA}$				0.4	V
V_{OH}	Output voltage high	$I_{OUT} = -1\text{ mA}$		$V_L - 0.6$	$V_L - 0.1$		V
V_{IT-}	Input threshold low	$T_A = 25^\circ\text{C}$	$V_L = 5\text{ V}$	0.8	1.2		V
			$V_L = 3.3\text{ V}$	0.6	1.5		
V_{IT+}	Input threshold high	$T_A = 25^\circ\text{C}$	$V_L = 5\text{ V}$		1.8	2.4	V
			$V_L = 3.3\text{ V}$		1.5	2.4	
V_{hys}	Input hysteresis				0.5		V
	Input resistance	$T_A = 25^\circ\text{C}$		3	5	7	k Ω

(1) Typical values are at $V_{CC} = V_L = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$

Switching Characteristics

over operating free-air temperature range, $V_{CC} = V_L = 3\text{ V}$ to 5.5 V , $C1\text{--}C4 = 0.1\text{ }\mu\text{F}$ (tested at $3.3\text{ V} \pm 10\%$), $C1 = 0.047\text{ }\mu\text{F}$, $C2\text{--}C4 = 0.33\text{ }\mu\text{F}$ (tested at $5\text{ V} \pm 10\%$), $T_A = T_{MIN}$ to T_{MAX} (unless otherwise noted)

PARAMETER		TEST CONDITIONS	TYP ⁽¹⁾	UNIT
t_{PHL}	Receiver propagation delay	Receiver input to receiver output, $C_L = 150\text{ pF}$	0.15	μs
t_{PLH}			0.15	
$t_{PHL} - t_{PLH}$	Receiver skew		50	ns
t_{en}	Receiver output enable time	From $\overline{\text{PWRDWN}}$	200	ns
t_{dis}	Receiver output disable time	From $\overline{\text{PWRDWN}}$	200	ns

(1) Typical values are at $V_{CC} = V_L = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

DRIVER SECTION

Electrical Characteristics

over operating free-air temperature range, $V_{CC} = V_L = 3\text{ V}$ to 5.5 V , C_1 – $C_4 = 0.1\text{ }\mu\text{F}$ (tested at $3.3\text{ V} \pm 10\%$), $C_1 = 0.047\text{ }\mu\text{F}$, C_2 – $C_4 = 0.33\text{ }\mu\text{F}$ (tested at $5\text{ V} \pm 10\%$), $T_A = T_{MIN}$ to T_{MAX} (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
V_{OH} Output voltage swing	All driver outputs loaded with $3\text{ k}\Omega$ to ground	± 5	± 5.4		V
r_o Output resistance	$V_{CC} = V_+ = V_- = 0$, Driver output = $\pm 2\text{ V}$	300	10M		Ω
I_{OS} Output short-circuit current	$V_{T_OUT} = 0$			± 60	mA
I_{OZ} Output leakage current	$V_{T_OUT} = \pm 12\text{ V}$, Driver disabled, $V_{CC} = 0$ or 3 V to 5.5 V			± 25	μA
Driver input hysteresis				0.5	V
Input leakage current	DIN, $\overline{\text{PWRDWN}}$		± 0.01	± 1	μA

(1) Typical values are at $V_{CC} = V_L = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$

Timing Requirements

over operating free-air temperature range, $V_{CC} = V_L = 3\text{ V}$ to 5.5 V , C_1 – $C_4 = 0.1\text{ }\mu\text{F}$ (tested at $3.3\text{ V} \pm 10\%$), $C_1 = 0.047\text{ }\mu\text{F}$, C_2 – $C_4 = 0.33\text{ }\mu\text{F}$ (tested at $5\text{ V} \pm 10\%$), $T_A = T_{MIN}$ to T_{MAX} (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
Maximum data rate	$R_L = 3\text{ k}\Omega$, $C_L = 1000\text{ pF}$, One driver switching	250			kbps
Time-to-exit powerdown	$ V_{T_OUT} > 3.7\text{ V}$		100		μs
$ t_{PHL} - t_{PLH} $ Driver skew ⁽²⁾			100		ns
Transition-region slew rate	$V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$, $R_L = 3\text{ k}\Omega$ to $7\text{ k}\Omega$, Measured from 3 V to -3 V or -3 V to 3 V	$C_L = 150\text{ pF}$ to 1000 pF	6	30	V/ μs
		$C_L = 150\text{ pF}$ to 2500 pF	4	30	

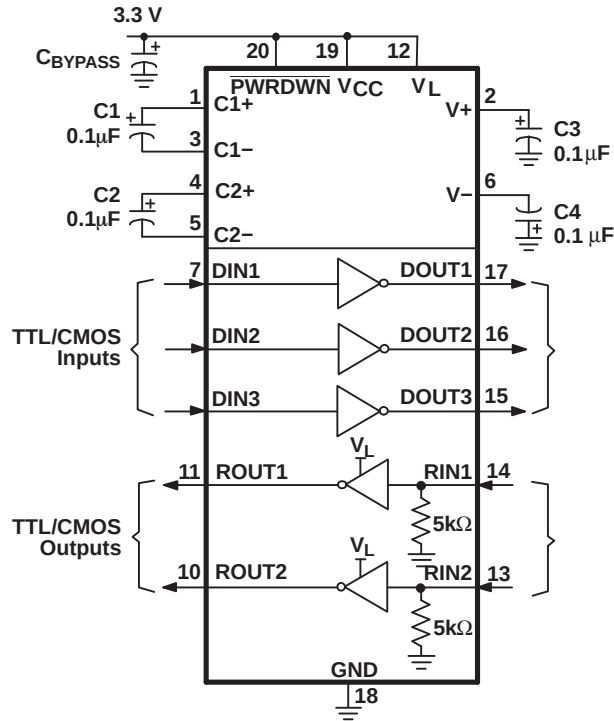
(1) Typical values are at $V_{CC} = V_L = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

(2) Driver skew is measured at the driver zero crosspoint.

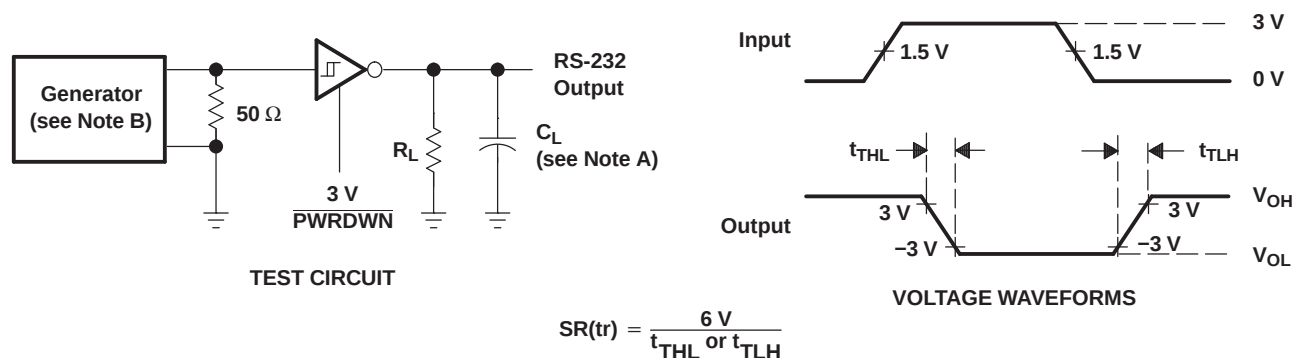
ESD Protection

PARAMETER	TEST CONDITIONS	TYP	UNIT
RIN, DOUT	Human-Body Model	± 15	kV
	IEC 61000-4-2 Air-Gap Discharge	± 15	
	IEC 61000-4-2 Contact Discharge	± 8	

APPLICATION INFORMATION



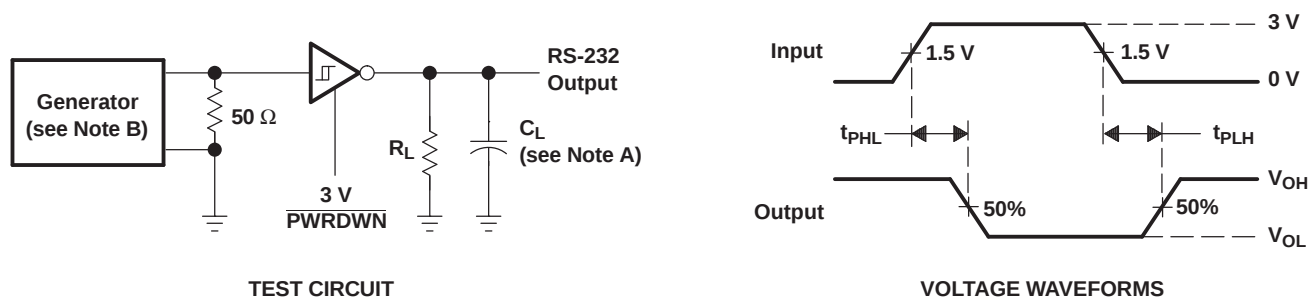
PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\text{ ns}$, $t_f \leq 10\text{ ns}$.

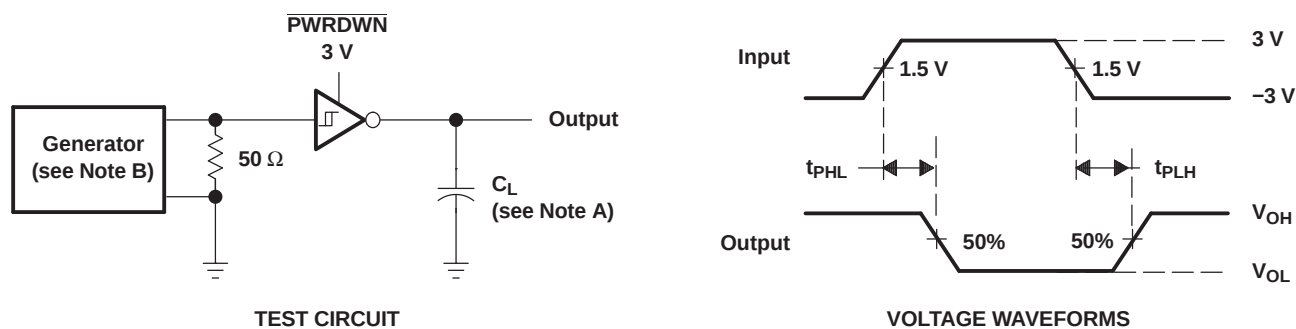
Figure 1. Driver Slew Rate



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\text{ ns}$, $t_f \leq 10\text{ ns}$.

Figure 2. Driver Pulse Skew

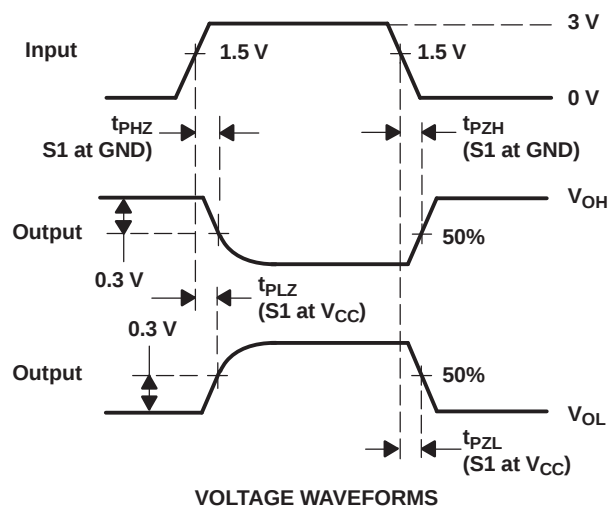
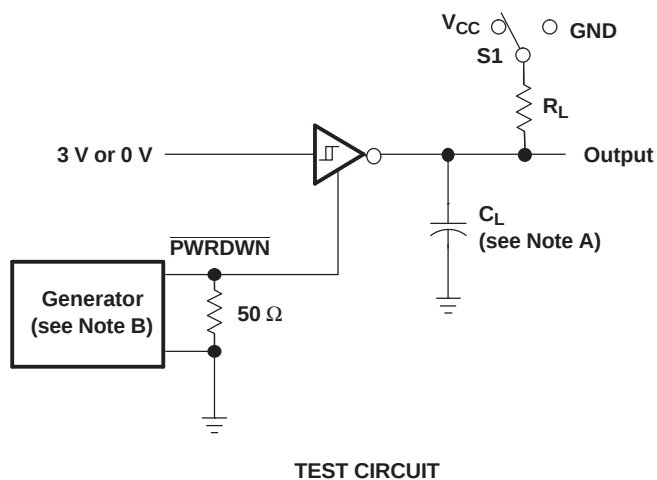


NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\text{ ns}$, $t_f \leq 10\text{ ns}$.

Figure 3. Receiver Propagation Delay Times

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\ \text{ns}$, $t_f \leq 10\ \text{ns}$.

Figure 4. Receiver Enable and Disable Times

REVISION HISTORY

Changes from Revision A (November 2008) to Revision B	Page
• Changed V_L Pin for Compatibility With Mixed-Voltage Systems Down to 2.5 V (originally 1.8 V) on the Logic Side	1
• Changed V_L Supply MIN value from 1.65 V to 2.25 V.	3
• Deleted $V_L = 1.65V$ parameter from Input logic threshold low.	3
• Deleted $V_L = 1.95V$ parameter from Input logic threshold high.	3

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
MAX3386ECDWR	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3386EC
MAX3386ECDWR.A	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3386EC
MAX3386ECPW	Obsolete	Production	TSSOP (PW) 20	-	-	Call TI	Call TI	0 to 70	MP386EC
MAX3386ECPWR	Obsolete	Production	TSSOP (PW) 20	-	-	Call TI	Call TI	0 to 70	MP386EC
MAX3386EIDW	Obsolete	Production	SOIC (DW) 20	-	-	Call TI	Call TI	-40 to 85	MAX3386EI
MAX3386EIDWR	Obsolete	Production	SOIC (DW) 20	-	-	Call TI	Call TI	-40 to 85	MAX3386EI
MAX3386EIPW	Obsolete	Production	TSSOP (PW) 20	-	-	Call TI	Call TI	-40 to 85	MP386EI
MAX3386EIPWR	Obsolete	Production	TSSOP (PW) 20	-	-	Call TI	Call TI	-40 to 85	MP386EI

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

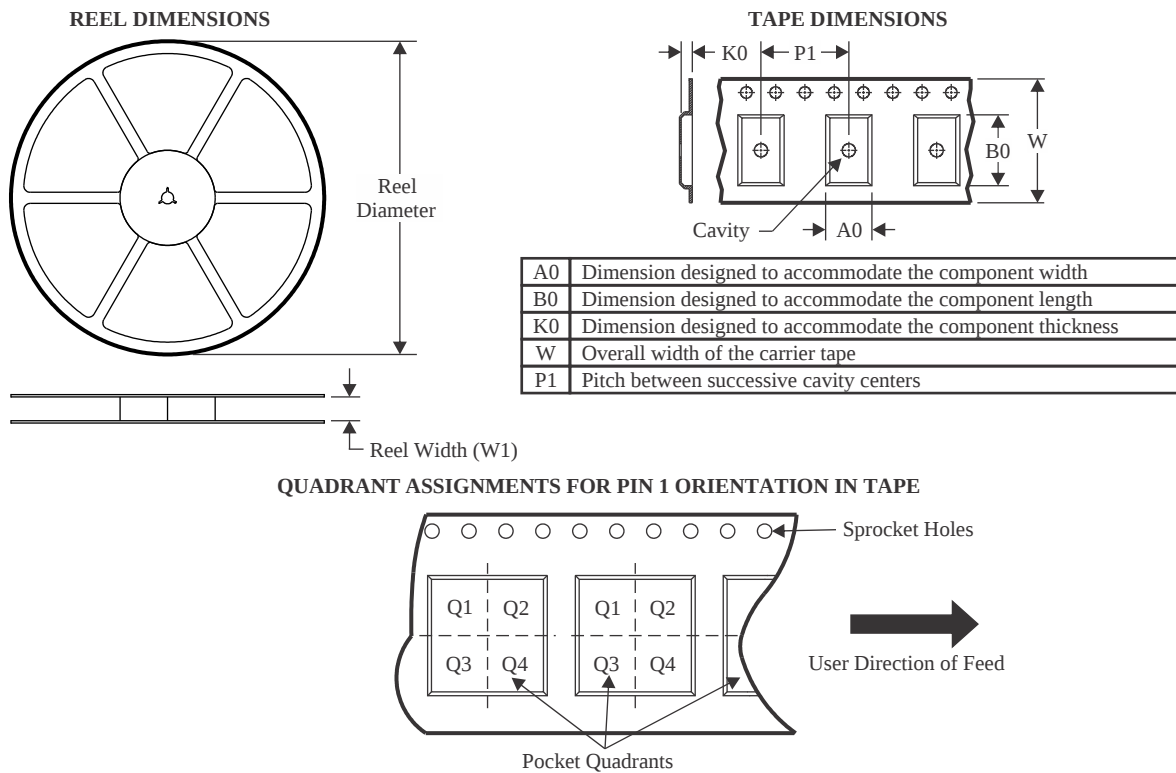
⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

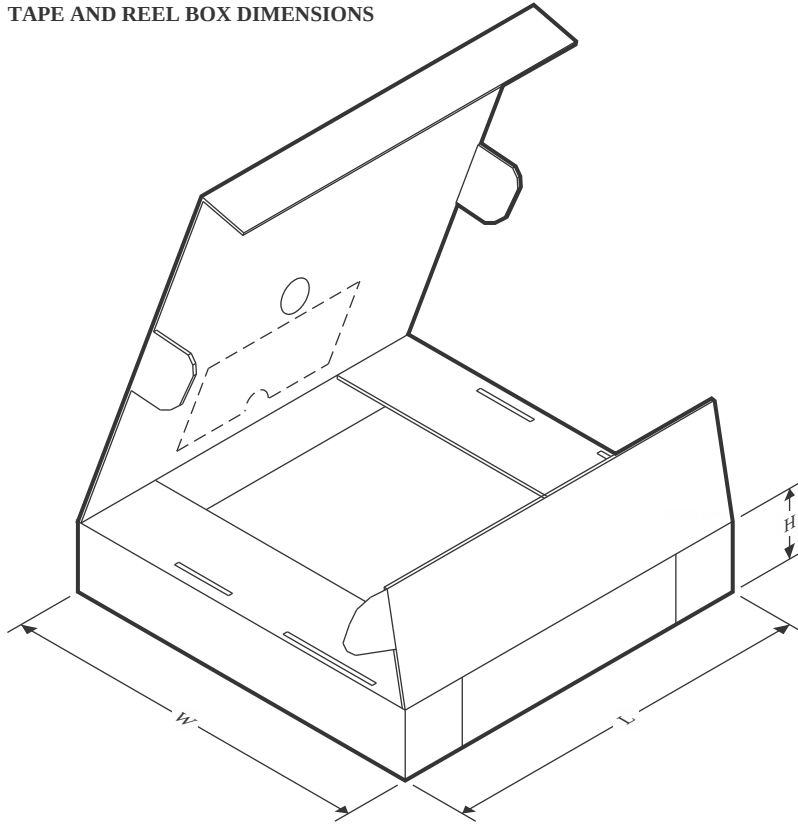
TAPE AND REEL INFORMATION



*All dimensions are nominal

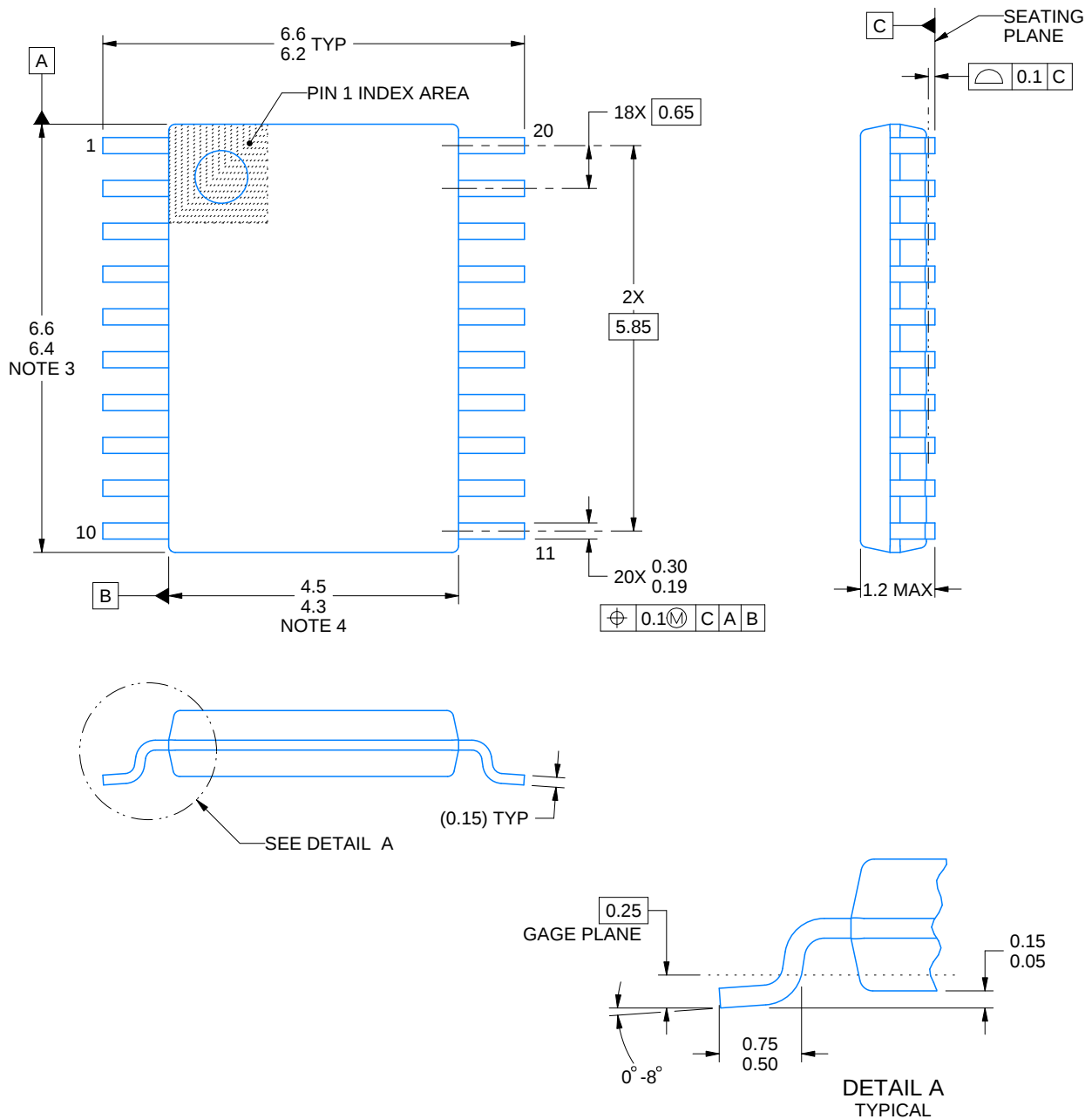
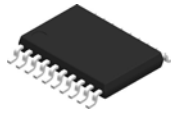
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MAX3386ECDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MAX3386ECDWR	SOIC	DW	20	2000	356.0	356.0	45.0



4220206/A 02/2017

NOTES:

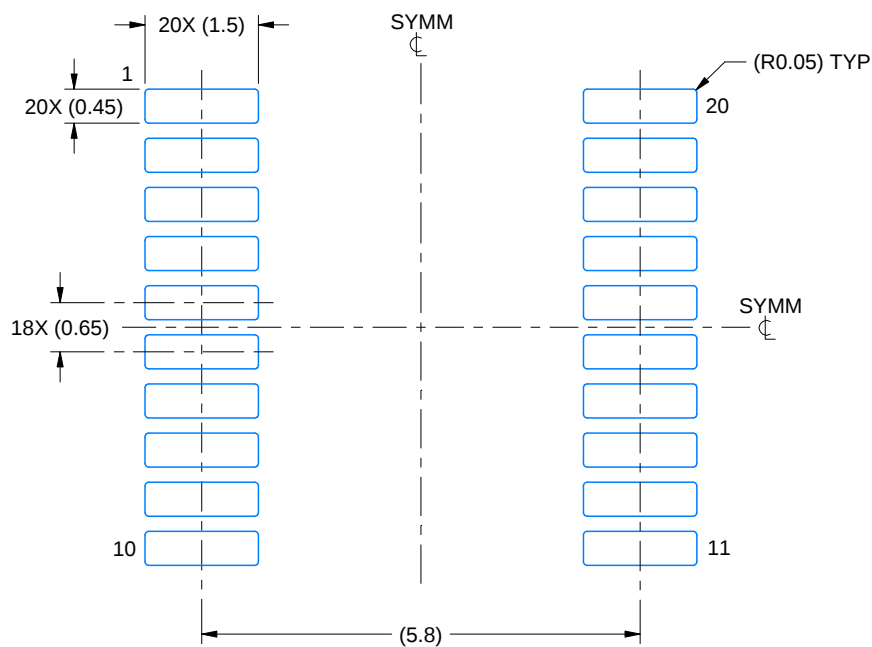
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

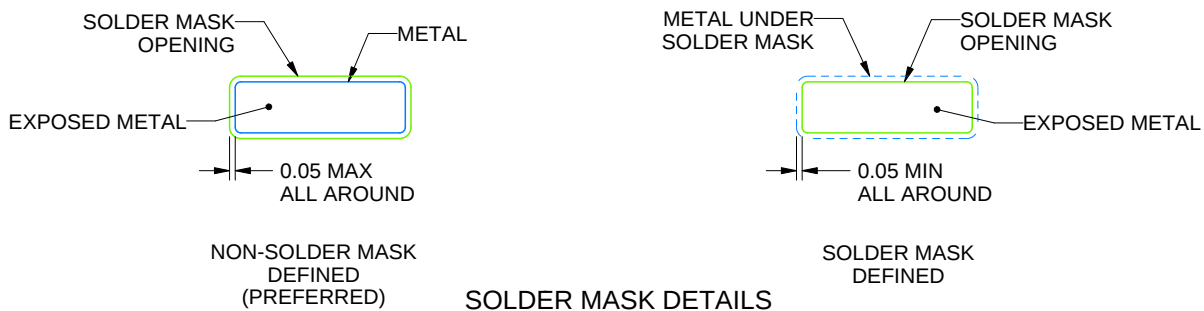
PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220206/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

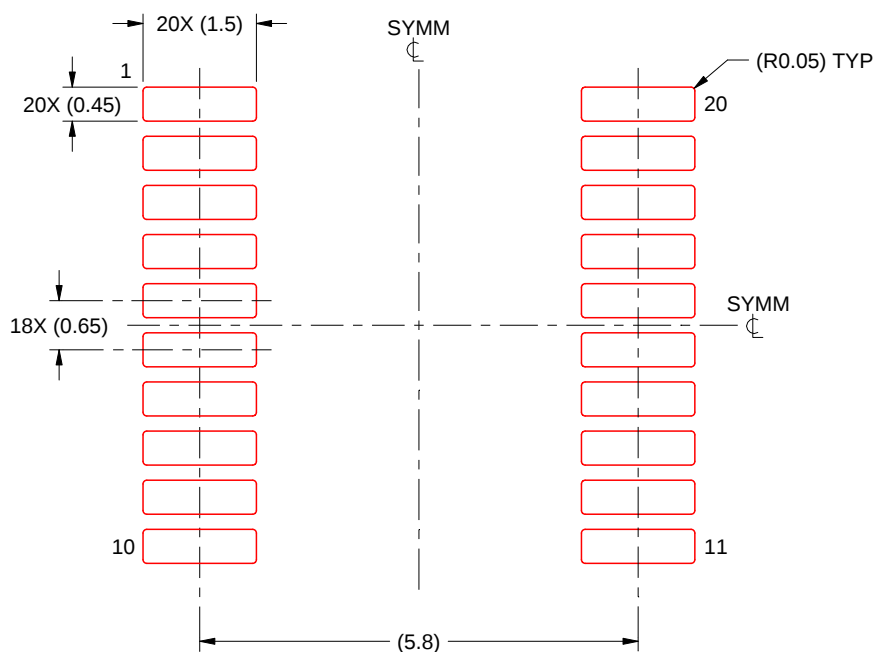
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

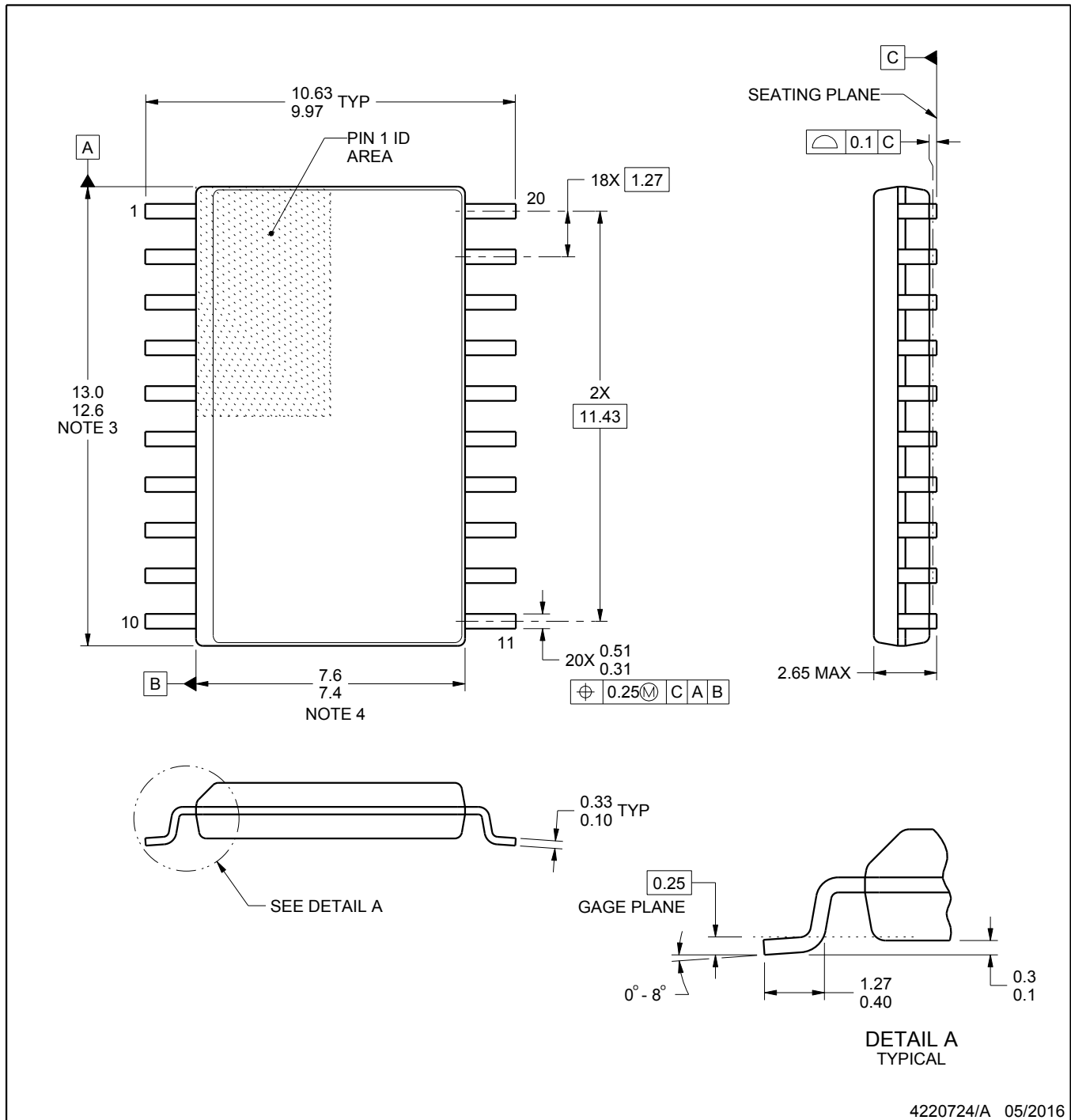
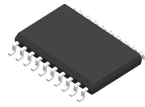


SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



NOTES:

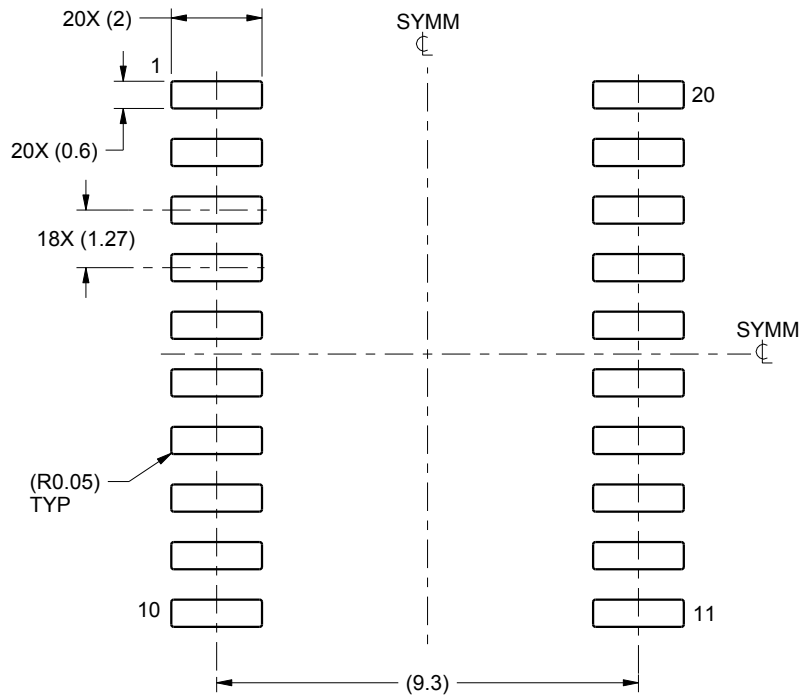
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

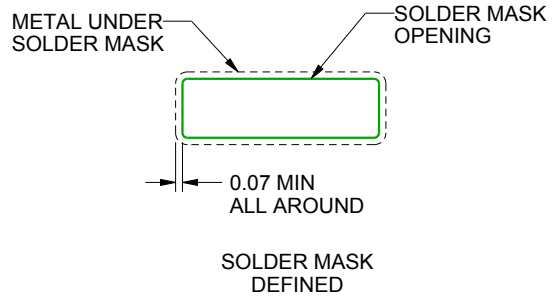
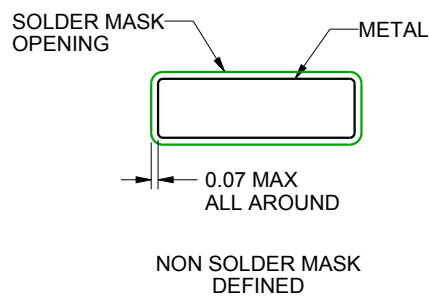
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

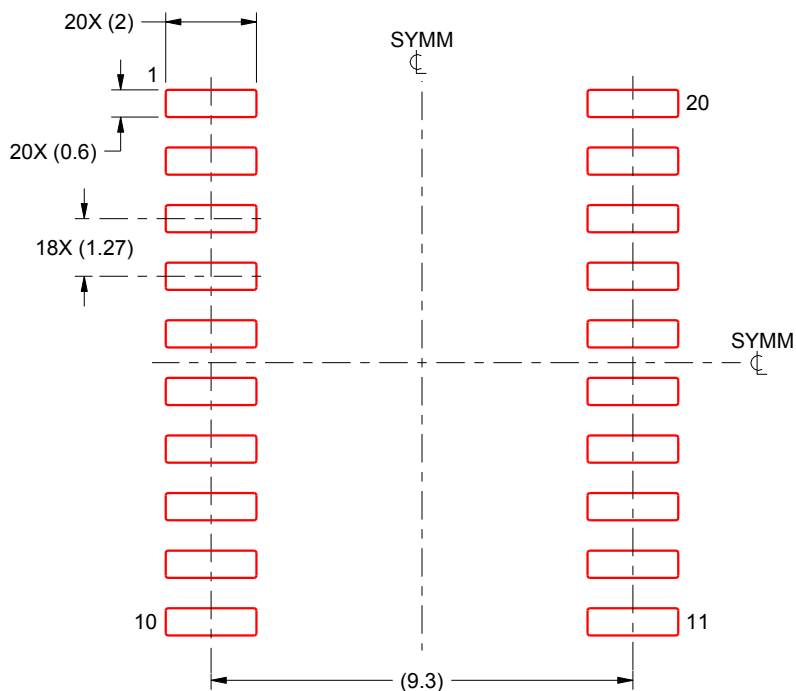
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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